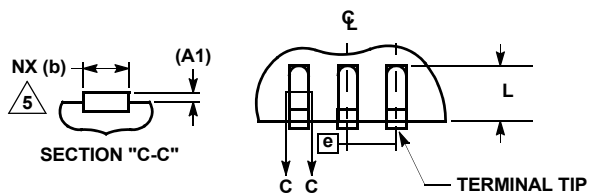
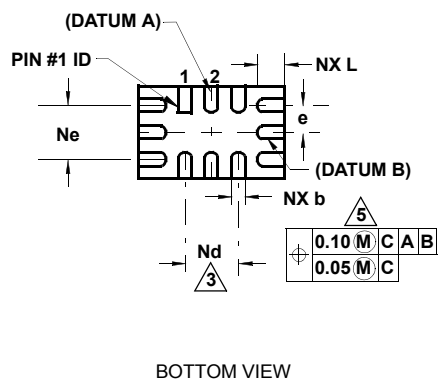
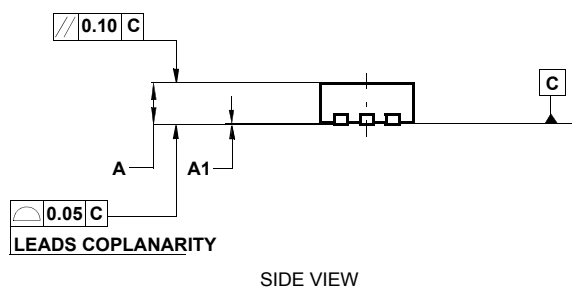
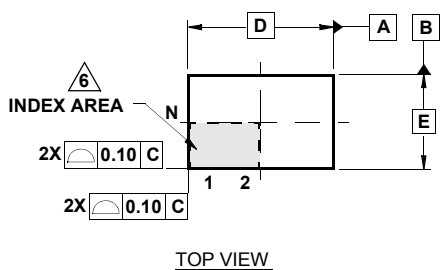


# Plastic Packages for Integrated Circuits

## Ultra Thin Quad Flat No-Lead Plastic Package (UTQFN)



### L12.2.2x1.4A

#### 12 LEAD ULTRA THIN QUAD FLAT NO-LEAD PLASTIC PACKAGE

SYMBOL	MILLIMETERS			NOTES
	MIN	NOMINAL	MAX	
A	0.45	0.50	0.55	-
A1	-	-	0.05	-
A3	0.127 REF			-
b	0.15	0.20	0.25	5
D	2.15	2.20	2.25	-
E	1.35	1.40	1.45	-
e	0.40 BSC			-
k	0.20	-	-	-
L	0.35	0.40	0.45	-
N	12			2
Nd	3			3
Ne	3			3
θ	0	-	12	4

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#### NOTES:

1. Dimensioning and tolerancing conform to ASME Y14.5-1994.
2. N is the number of terminals.
3. Nd and Ne refer to the number of terminals on D and E side, respectively.
4. All dimensions are in millimeters. Angles are in degrees.
5. Dimension b applies to the metallized terminal and is measured between 0.15mm and 0.30mm from the terminal tip.
6. The configuration of the pin #1 identifier is optional, but must be located within the zone indicated. The pin #1 identifier may be either a mold or mark feature.
7. Maximum package warpage is 0.05mm.
8. Maximum allowable burrs is 0.076mm in all directions.
9. Same as JEDEC MO-255UABD except:  
No lead-pull-back, "A" MIN dimension = 0.45 not 0.50mm  
"L" MAX dimension = 0.45 not 0.42mm.
10. For additional information, to assist with the PCB Land Pattern Design effort, see Intersil Technical Brief TB389.

